

In re Patent Application of:
PIKE ET AL.
Serial No. 09/741,754
Filed: December 19, 2000

In the Specification:

Please amend the paragraph beginning at page 1, line 14 as follows:

As the density of active devices on typical integrated circuits has increased, dissipation of the heat generated has become ~~increasing~~ increasingly more important. Designers have developed cooling techniques for integrated circuits based on micro-electromechanical (MEMS) technology.

Please amend the paragraph beginning at page 1, line 20, as follows:

For example, as shown in FIG. 1, a prior art electronic device 10 includes a package 11 including a first member 12 comprising silicon, and a second member 14 comprising a low temperature ~~co-fired~~ co-fired ceramic (LTCC) material. The first member 12 may include several stacked silicon substrates 12a, 12b having various components of a micro-fluidic cooler formed therein. For example, as shown in the illustrated embodiment, an evaporator 16 and condensor 17 may be provided and interconnected via one or more micro-fluidic channels or passageways 21 formed between the silicon substrates 12a, 12b. One or more MEMS pumps, not shown, may circulate the cooling fluid.